



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



580801RS

('ON 0NIMVHD) 台線理図

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.

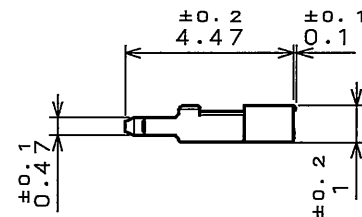
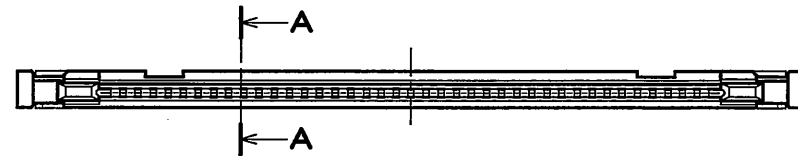
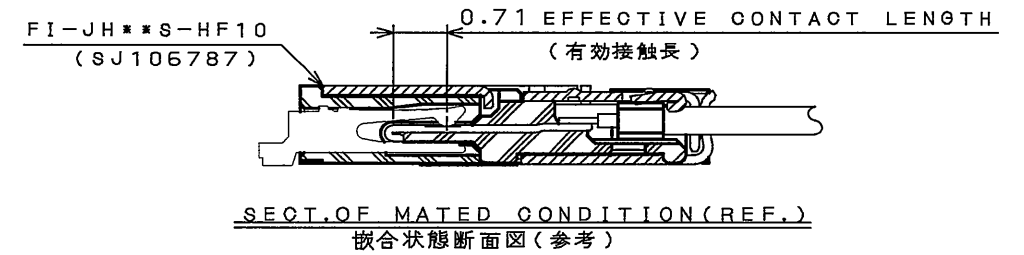
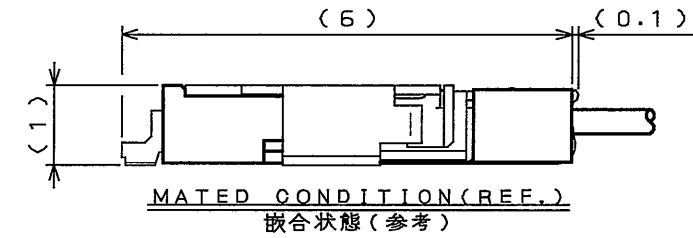
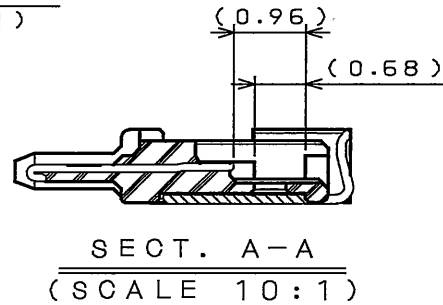
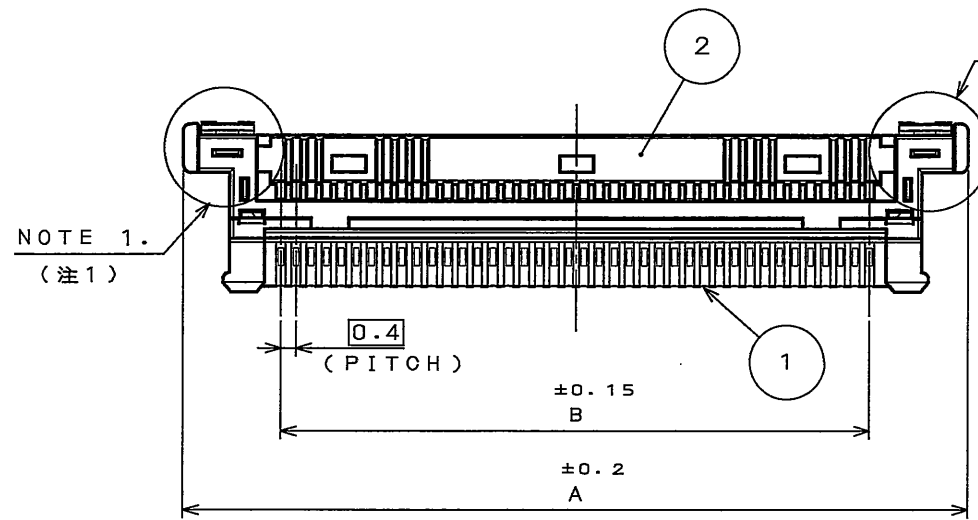


TABLE 1

No. OF CONTACTS	A	B
40	20.8	15.6
30	16.8	11.6

NOTE1. CONFIGURATION OF GATE IS DIFFERENT, DEPENDING ON TOOLING OF MOLD.
SEE THE FIGURE1 AND FIGURE2.
注1.ゲート形状は成形時の金型により異なります。
図1,図2を参照ください。

GATE RESIDUE AT MOLDING OF TYPE1 (タイプ1のモールド成形時のゲート残りを示す)

GATE RESIDUE AT MOLDING OF TYPE2 (タイプ2のモールド成形時のゲート残りを示す)

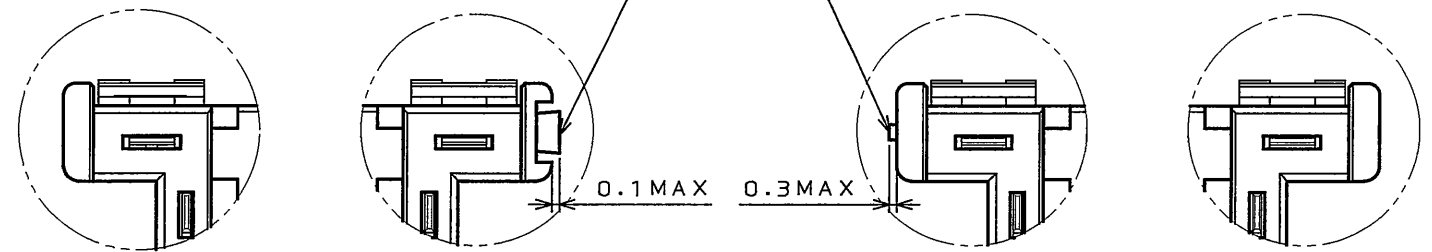
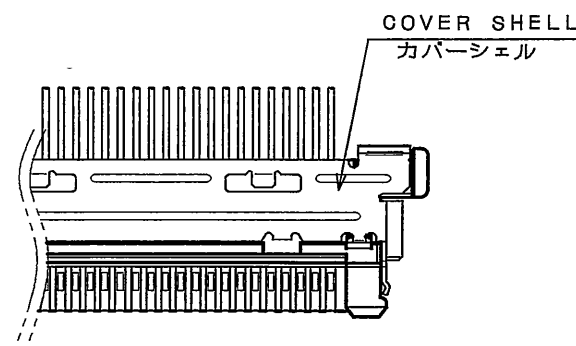
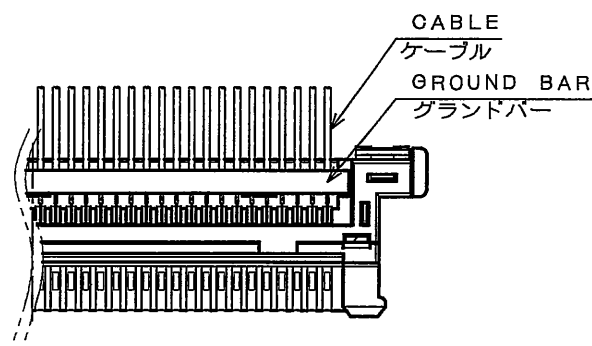
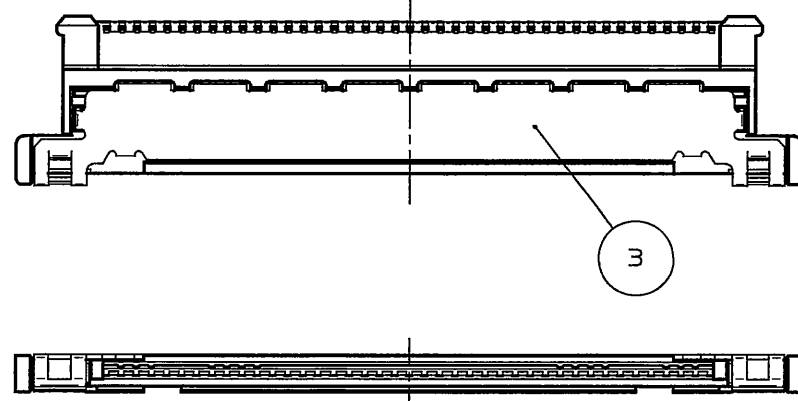


FIGURE 1. TYPE1

FIGURE 2. TYPE2



CABLE ASSEMBLED CONDITION (REF.)
ケーブル組込状態図(参考)

COVER SHELL ASSEMBLED CONDITION (REF.)
カバーシェル組込状態図(参考)

3	BASE SHELL ベースシェル	1	STAINLESS STEEL ステンレス	GOLD(0.03μmMIN)OVER NICKEL Ni+Au>μ*(0.03μm以上)	
2	INSULATOR インシュレータ	1	HAET RESISTING PLASTIC 耐熱性樹脂		
1	CONTACT コンタクト	**	COPPER ALLOY 銅合金	CONTACT AREA:GOLD(0.1μmMIN)OVER NICKEL 接触部:NI+Au(0.1μm以上)μ*μ	TERMINAL AREA: GOLD(0.03μmMIN)OVER NICKEL
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
仕様書(SPECIFICATION) JACS-10363-*		第1版(ORIGINAL DATE) 4.Dec.2007		尺度(SCALE) 5:1	シリーズ(SERIES) FI-JH
一般公差(GENERAL TOLERANCE)		製図 DR.		名称(TITLE) FI-JH**C-B	
寸法(DIMENSION)		担当 CHK. T.TSUJI		日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
角度(ANGLES)		査閲 APPD. M. Hukuchi		図面番号(DRAWING NO.) SJ108085	
±	° ±	承認 APPD. K. Hsotomi		版数 (REV.) 1	
.X ±	.X° ±				
.XX ±	.XX° ±				
.XXX ±	.XXX° ±				

DOF-0-212F(05.08)

